

RMLV0408E Series

4Mb Advanced LPSRAM (512-kword × 8-bit)

R10DS0206EJ0300 Rev.3.00 2021.8.18

Description

The RMLV0408E Series is a family of 4-Mbit static RAMs organized 524,288-word × 8-bit, fabricated by Renesas's high-performance Advanced LPSRAM technologies. The RMLV0408E Series has realized higher density, higher performance and low power consumption. The RMLV0408E Series offers low power standby power dissipation; therefore, it is suitable for battery backup systems. It is offered in 32-pin SOP, 32-pin TSOP (II) or 32-pin sTSOP.

Features

• Single 3V supply: 2.7V to 3.6V

• Access time: 45ns (max.)

• Current consumption:

— Standby: 0.3μA (typ.)

• Equal access and cycle times

• Common data input and output

- Three state output

• Directly TTL compatible

— All inputs and outputs

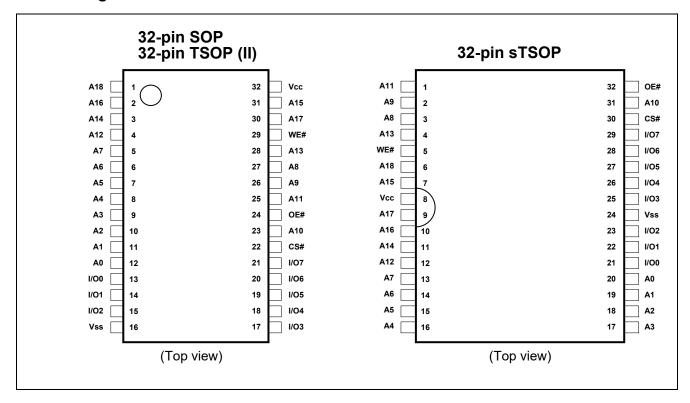
• Battery backup operation

Orderable part number information

Orderable part number	Access time	Temperature range	Package	Shipping container
RMLV0408EGSA-4S2#AA*			8mm×13.4mm 32-pin	Tray
RMLV0408EGSA-4S2#KA*			plastic sTSOP	Embossed tape
RMLV0408EGSB-4S2#AA*	45 ns	-40 ~ +85°C	400-mil 32pin	Tray
RMLV0408EGSB-4S2#HA*	43115	-40 ° +63 C	plastic TSOP (II)	Embossed tape
RMLV0408EGSP-4S2#CA*			525-mil 32-pin	Tube
RMLV0408EGSP-4S2#HA*			plastic SOP	Embossed tape

Note 1. * = Revision code for Assembly site change, etc. (* = 0, 1, etc.)

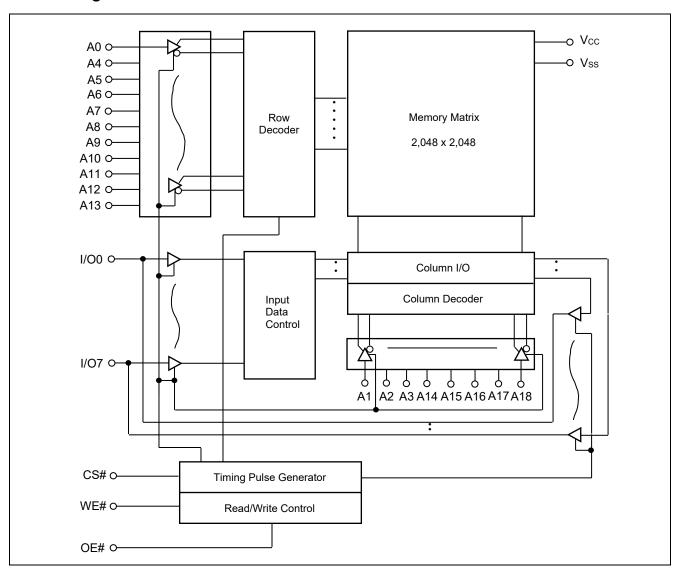
Pin Arrangement



Pin Description

Pin name	Function	
Vcc	Power supply	
Vss	Ground	
A0 to A18	Address input	
I/O0 to I/O7	Data input/output	
CS#	Chip select	
WE#	Write enable	
OE#	Output enable	

Block Diagram



Operation Table

CS#	WE#	OE#	I/O0 to I/O7	Operation
Н	Х	Χ	High-Z	Standby
L	Н	L	Dout	Read
L	L	Х	Din	Write
L	Н	Н	High-Z	Output disable

Note 2. H: VIH L:VIL X: VIH or VIL

Absolute Maximum Ratings

Parameter	Symbol	Value	unit
Power supply voltage relative to Vss	Vcc	-0.5 to +4.6	V
Terminal voltage on any pin relative to Vss	VT	-0.5*3 to V _{CC} +0.3*4	V
Power dissipation	PT	0.7	W
Operation temperature	Topr	-40 to +85	°C
Storage temperature range	Tstg	-65 to +150	°C
Storage temperature range under bias	Tbias	-40 to +85	°C

Note 3. -3.0V for pulse \leq 30ns (full width at half maximum)

4. Maximum voltage is +4.6V.

DC Operating Conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	2.7	3.0	3.6	V	
	Vss	0	0	0	V	
Input high voltage	VIH	2.2	-	V _{CC} +0.3	V	
Input low voltage	VIL	-0.3	-	0.6	V	5
Ambient temperature range	Та	-40	_	+85	°C	

Note 5. -3.0V for pulse ≤ 30ns (full width at half maximum)

DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit		Test conditions			
Input leakage current	[[]	_	-	1	μА	Vin = Vss	Vin = Vss to Vcc			
Output leakage current	110	_	_	1	μА	CS# = V _{II} - VI/O = V _{SS}	or OE# =V _{IH} or WE#= V _{IL} ,			
Operating current	Icc	_	_	10	mA	CS# =V _{IL} ,				
Average operating current		_	_	20	mA	-	5ns, duty = 100%, II/O = 0mA, , Others = V _{IH} /V _{IL}			
	Icc1	_	ı	25	mA	-	5ns, duty = 100%, II/O = 0mA, , Others = V _{IH} /V _{IL}			
	Icc2	_	_	2.5	mA	1 -	µs, duty = 100%, II/O = 0mA, 2V, V _{IH} ≥ Vcc-0.2V, V _{IL} ≤ 0.2V			
Standby current	I _{SB}	_	0.1 ^{*6}	0.3	mA	1	CS# =V _{IH} , Others = Vss to Vcc			
Standby current		_	0.3*6	2	μА	~+25°C				
		_	_	3	μА	~+40°C	Vin = Vss to Vcc,			
	I _{SB1}	_	_	5	μА	~+70°C	CS# ≥ V _{CC} -0.2V			
		_	_	7	μА	~+85°C				
Output high voltage	Vон	2.4	_	_	V	I _{OH} = -1mA				
	V _{OH2}	Vcc-0.2	_	_	V	I _{OH} = -0.1mA				
Output low voltage	Vol	_	_	0.4	V	I _{OL} = 2.1mA				
	V _{OL2}	_	_	0.2	V	I _{OL} = 0.1m	I _{OL} = 0.1mA			

Note 6. Typical parameter indicates the value for the center of distribution at 3.0V (Ta=25°C), and not 100% tested.

Capacitance

 $(Vcc = 2.7V \sim 3.6V, f = 1MHz, Ta = -40 \sim +85^{\circ}C)$

			•		-	•	,
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions	Note
Input capacitance	C in	_	_	8	pF	Vin =0V	7
Input / output capacitance	C 1/0	_	_	10	pF	V _{I/O} =0V	7

Note 7. This parameter is sampled and not 100% tested.

AC Characteristics

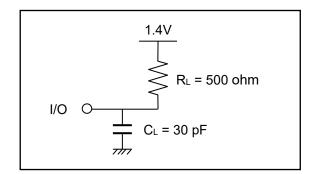
Test Conditions (Vcc = $2.7V \sim 3.6V$, Ta = $-40 \sim +85$ °C)

• Input pulse levels: $V_{IL} = 0.4V$, $V_{IH} = 2.4V$

• Input rise and fall time: 5ns

• Input and output timing reference level: 1.4V

• Output load: See figures (Including scope and jig)



Read Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Read cycle time	t _{RC}	45	_	ns	
Address access time	t _{AA}	ı	45	ns	
Chip select access time	t _{ACS}	1	45	ns	
Output enable to output valid	t _{OE}	1	22	ns	
Output hold from address change	t _{OH}	10	1	ns	
Chip select to output in low-Z	t _{CLZ}	10	1	ns	8,9
Output enable to output in low-Z	t _{OLZ}	5	1	ns	8,9
Chip deselect to output in high-Z	t _{CHZ}	0	18	ns	8,9,10
Output disable to output in high-Z	t _{OHZ}	0	18	ns	8,9,10

Write Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Write cycle time	twc	45	_	ns	
Address valid to write end	t _{AW}	35	_	ns	
Chip select to write end	tcw	35	_	ns	
Write pulse width	twp	35	_	ns	11
Address setup time to write start	t _{AS}	0	_	ns	
Write recovery time from write end	t _{WR}	0	_	ns	
Data to write time overlap	t _{DW}	25	_	ns	
Data hold from write end	t _{DH}	0	_	ns	
Output enable from write end	tow	5	_	ns	8
Output disable to output in high-Z	t _{OHZ}	0	18	ns	8,10
Write to output in high-Z	t _{WHZ}	0	18	ns	8,10

Note 8. This parameter is sampled and not 100% tested.

- 9. At any given temperature and voltage condition, t_{CHZ} max is less than t_{CLZ} min, and t_{OHZ} max is less than t_{OLZ} min, for any device.
- 10. t_{CHZ} , t_{OHZ} and t_{WHZ} are defined as the time when the I/O pins enter a high-impedance state and are not referred to the I/O levels.
- 11. t_{WP} is the interval between write start and write end.

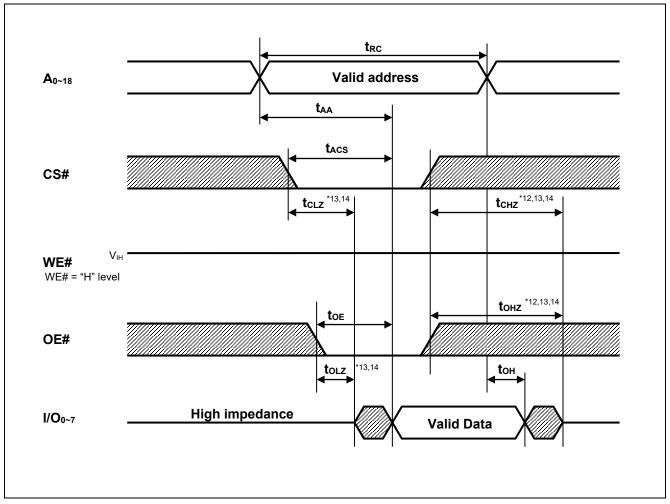
A write starts when both of CS# and WE# become active

A write is performed during the overlap of a low CS#, a low WE#

A write ends when any of CS#, WE# becomes inactive.

Timing Waveforms

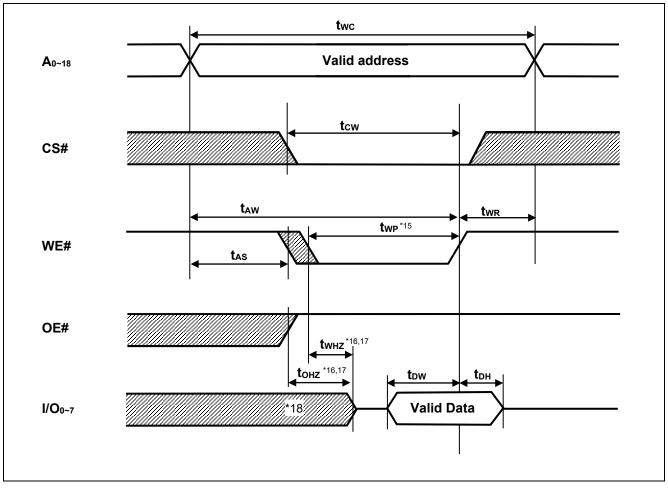
Read Cycle



Note 12. t_{CHZ} and t_{OHZ} are defined as the time when the I/O pins enter a high-impedance state and are not referred to the I/O levels.

- 13. This parameter is sampled and not 100% tested.
- 14. At any given temperature and voltage condition, t_{CHZ} max is less than t_{CLZ} min, and t_{OHZ} max is less than t_{OLZ} min, for any device.

Write Cycle (1) (WE# CLOCK, OE#="H" while writing)



Note 15. twp is the interval between write start and write end.

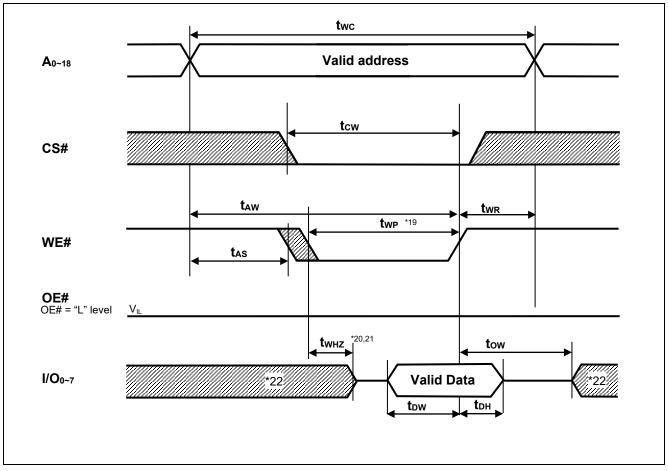
A write starts when both of CS# and WE# become active.

A write is performed during the overlap of a low CS# and a low WE#.

A write ends when any of CS# or WE# becomes inactive.

- 16. t_{OHZ} and t_{WHZ} are defined as the time when the I/O pins enter a high-impedance state and are not referred to the I/O levels.
- 17. This parameter is sampled and not 100% tested.
- 18. During this period, I/O pins are in the output state so input signals must not be applied to the I/O pins.

Write Cycle (2) (WE# CLOCK, OE# Low Fixed)



Note 19. twp is the interval between write start and write end.

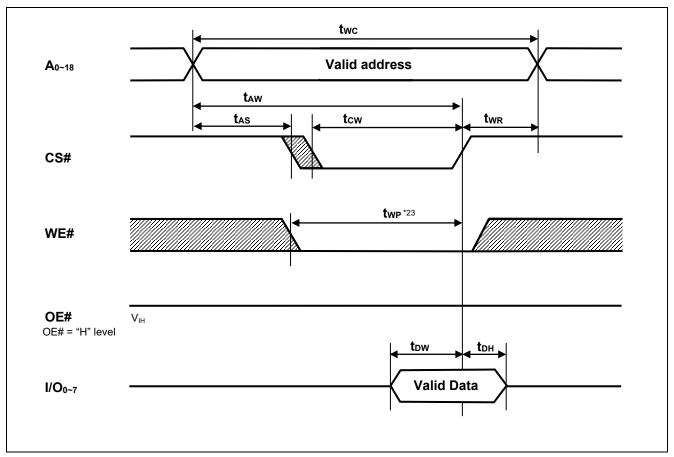
A write starts when both of CS# and WE# become active.

A write is performed during the overlap of a low CS# and a low WE#.

A write ends when any of CS# or WE# becomes inactive.

- 20. t_{WHZ} is defined as the time when the I/O pins enter a high-impedance state and are not referred to the I/O levels.
- 21. This parameter is sampled and not 100% tested.
- 22. During this period, I/O pins are in the output state so input signals must not be applied to the I/O pins.

Write Cycle (3) (CS# CLOCK)



Note 23. t_{WP} is the interval between write start and write end.

A write starts when both of CS# and WE# become active.

A write is performed during the overlap of a low CS# and a low WE#.

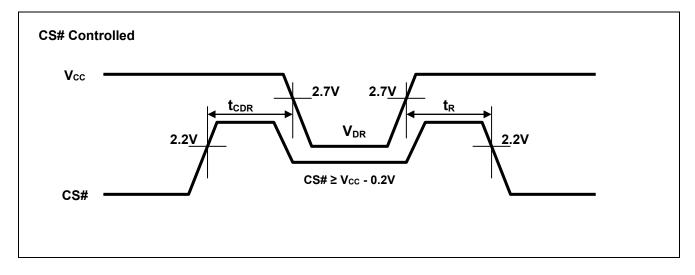
A write ends when any of CS# or WE# becomes inactive.

Low V_{CC} Data Retention Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions*25		
V _{CC} for data retention	V_{DR}	1.5	_	ı	V	$Vin \ge 0V,$ $CS\# \ge V_{CC}-0.2V$		
		_	0.3*24	2	μА	~+25°C		
	ICCDR	_	_	3	μА	~+40°C	V _{CC} =3.0V, Vin ≥ 0V,	
Data retention current		_	_	5	μА	~+70°C	CS#≥ Vcc-0.2V	
		_	_	7	μА	~+85°C		
Chip deselect time to data retention	t _{CDR}	0	-	_	ns	See retention waveform.		
Operation recovery time	t _R	5	_	_	ms			

Note 24. Typical parameter indicates the value for the center of distribution at 3.0V (Ta=25°C), and not 100% tested.

Low Vcc Data Retention Timing Waveforms (CS# controlled)



^{25.} CS# controls address buffer, WE# buffer, OE# buffer, and I/O buffer. If CS# controls data retention mode, Vin levels (address, WE#, OE#, I/O) can be in the high-impedance state.

Revision History

RMLV0408E Series Data Sheet

		Description					
Rev.	Date	Page	Summary				
1.00	2014.2.27	_	First edition issued				
2.00	2016.1.12	1	Changed section from "Part Name Information" to "Orderable part number information"				
2.01	2020.2.20	Last page	Updated the Notice to the latest version				
3.00	2021.8.18	1,4,10	Changed the typical value of I_{SB1} and I_{CCDR} from $0.4\mu A$ to $0.3\mu A$. Revised orderable part number information				
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